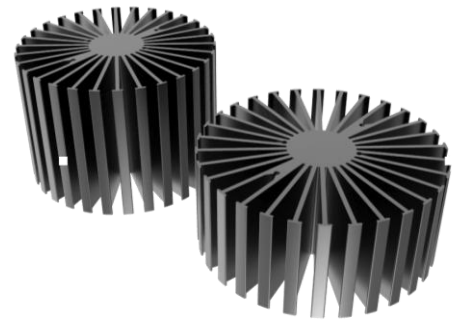




**SimpoleD** *SimpoleD-117 Series Star Heat Sinks  $\Phi$ 117mm for COB Modular Product Brief*

**Features VS Benefits**

- \* Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
  - \* Thermal resistance range Rth (0.96°C/W; 1.1°C/W).
  - \* Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's:
  - \* Diameter 117mm - Standard height 50.0mm / 80.0mm , Other heights on request.
  - \* Extruded from highly conductive aluminum.
- 2 standard colors - clear anodised - black anodised
- Zhaga Book 3 Spot Light Modules Edison, Bridgelux , Osram , Citizen , Lumileds , Cree , Tridonic , Vossloh-Schwabe , Seoul , LG , Lustrous , Prolight , Samsung , SHARP , Luminus



- 01) Bridgelux ESS, ESR, Vero 10;
- 02) Citizen CLL022-CLU024, CLL032-CLU034;
- 03) Cree XLamp CXA13xx, CXA15xx, CSA18xx;
- 04) Lumileds Luxeon COB's 1203, 1204, 1205, Luxeon K arrays K12, K16;
- 05) Osram PrevaLED Core, SOLERIQ P and SOLERIQ S LED engines.
- 06) Seoul Semiconductor ZC6, ZC12, ZC18, ZC25;
- 07) Tridonic TALEXX module SLE modules;
- 08) LG Innotek LEMWM18 10W, 13W, 17W
- 09) Edison EdiLex SLM and EdiLex II COB LED engines.
- 10) Lustrous LUSTRON 6 series LL604F, LL608D, LL613F, LL620F
- 11) Prolight Opto PABS, PABA, PACB, PANA
- 12) Samsung LC013, LC019, LC026 COB LED engines.
- 13) SHARP Mini Zenigata Intermo and Mega Zenigata LED engines.
- 14) Vossloh-Schwabe LUGA Shop LED engines.
- 15) Luminus C##9, C##14 LED engines.

**Order Information**

Example: **SimpoleD-11750-B-#**

Example: **SimpoleD-117** 1 - 2 - 3

1 Hight (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

Ex.order code - 12

means option 1 and 2 combined

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, a thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

**Notes:**

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.



**SimpoleD** SimpoLED-117 Series Star Heat Sinks  $\Phi$ 117mm for COB Modular Product Brief

**The product data table**

Brand	<b>Mingfa Tech</b>	
Series Name	SimpoleD star heat sinks	
Seriest Number	SimpoleD-117	
Manufacturing Technology	Aluminum extrusion	
Material	AL6063-T5	
Color & Finishing	Black Anodized	
Certification	CE, ROHS, WEEE	
Diameter(mm)	$\Phi$ 117	
Height(mm)	50.0mm	80.0mm
Item Number	SimpoleD-11750	SimpoleD-11780
Max. Lumen	6500 lm	7500 lm
Dissipated Power (Ths-amb,50°C)	45.0 W	52.0 W
Thermal Resistance Rth (°C/W)	1.1°C/W	0.96 °C/W
Cooling Surface Area (mm²)	147370.0 mm²	231490.0 mm²
Net Weight (g)	484.0 g	774.0 g
Quantity (pcs/CTN)	36 pcs	18 pcs
Modular Types	COB	COB
For Environments	Indoor area	
For Lightings	Down lights,Architectural lights	
For Application	Retail & Hospitality,Mall & Food,Architectural & Museums,Office & Education, Station & Airport,Healthcare	
For LED brands	Adura,Bridgelux,BJB,Citizen,Cree,Edison,GE,LG,Lumileds,Lumens,Luminus,Ledil,Nichia, Osram,Prolight Opto,Samsung,Seoul,Sharp,Tridonic,Vossloh Schwabe,Zhaga	

\* 3D files are available in ParaSolid, STP and IGS on request

\* The thermal resistance Rth is determined with a calibrated heat source of 14mmx14mm central placed on the heat sink, Tamb 40° and an open environment. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C  
The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power Pd

\* Dissipated power Pd. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C  
The maximal dissipated power needs to be verified in function of required case temperature Tc or junction temperature Tj and related to the estimated ambient temperature where the light fixture will be placed  
Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module

To calculate the dissipated power please use the following formula:  $Pd = Pe \times (1-\eta L)$

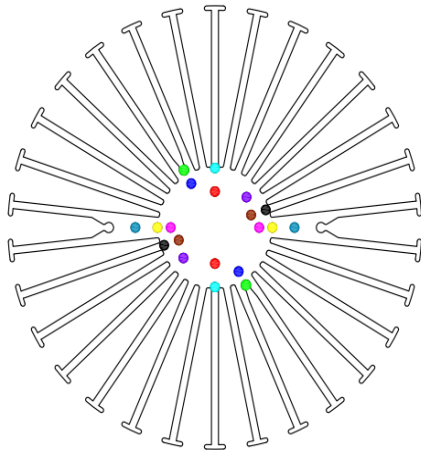
Pd - Dissipated power

Pe - Electrical power

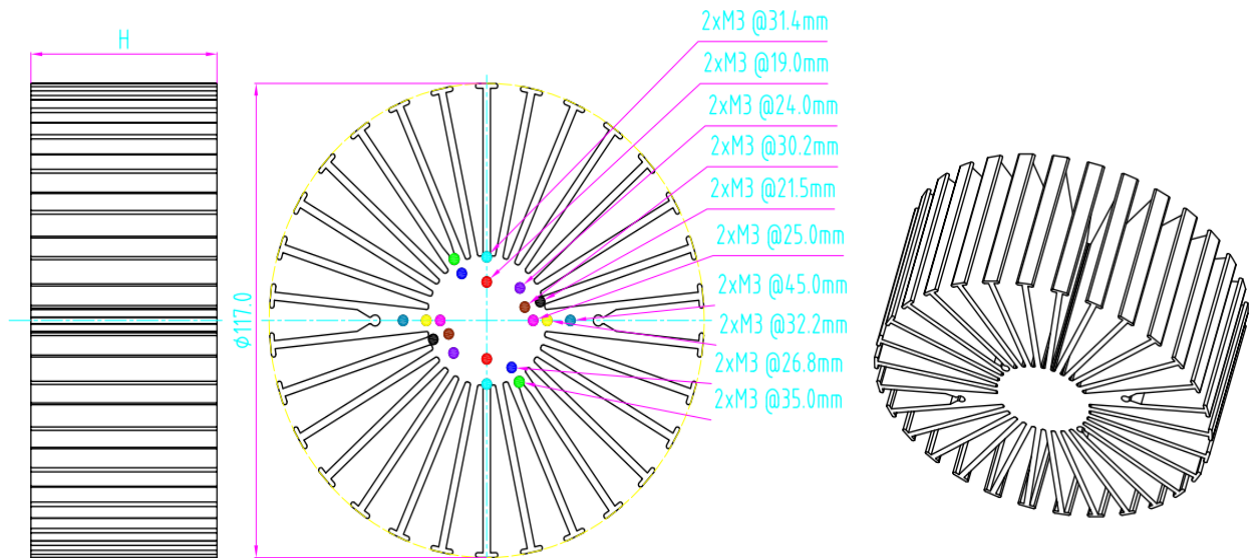
$\eta L$  = Light efficiency of the LED module

*SimpoLED* SimpoLED-117 Series  $\Phi 117\text{mm}$  COB Heat Sink Drawings

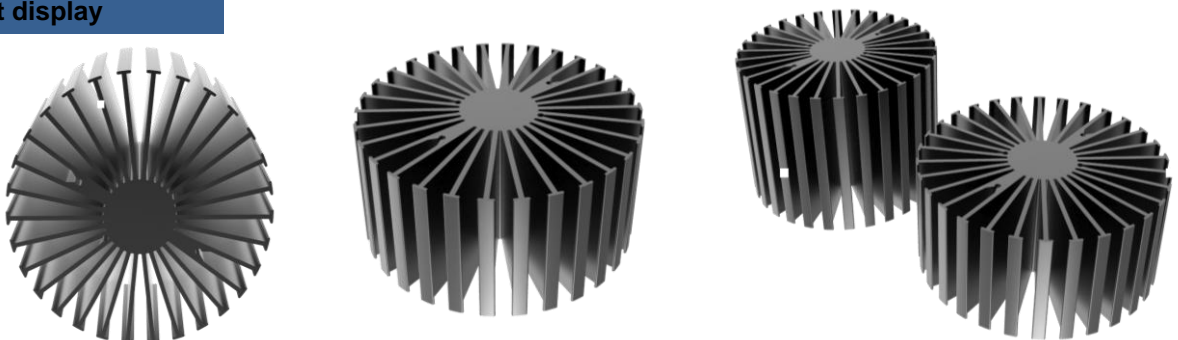
Drawings & Type Selection



MOUNTING OPTION	THREAD HOLE DISTANCE
A1	● 19.0 mm @ 2-180°
A2	● 21.5 mm @ 2-180°
A3	● 24.0 mm @ 2-180°
A4	● 25.0 mm @ 2-180°
A5	● 26.8 mm @ 2-180°
A6	● 30.2 mm @ 2-180°
A7	● 31.4 mm @ 2-180°
A8	● 32.2 mm @ 2-180°
A9	● 35.0 mm @ 2-180°
A10	● 45.0 mm @ 2-180°



Product display



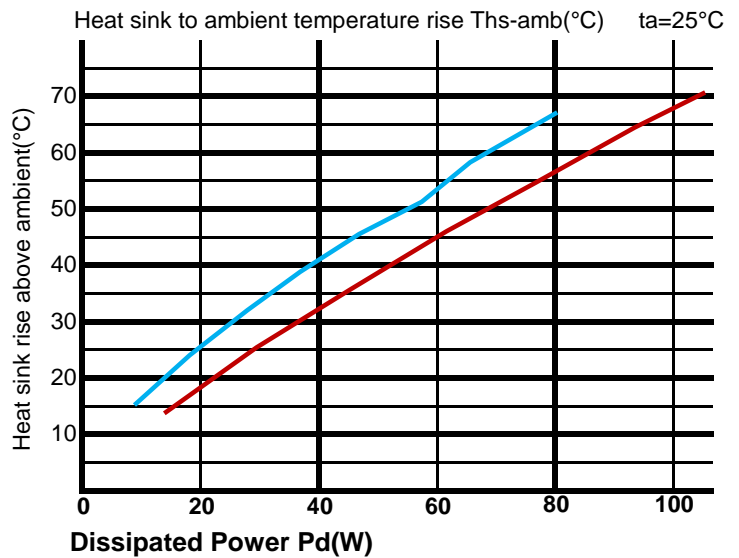


**SimpoleD** SimpoleD-117 Series  $\Phi 117\text{mm}$  Material AL6063-T5 COB Star Heat Sinks Thermal Data

**The thermal data table**

**SimpoleD-11780 thermal data**

Dissipated Power Pd(W)	Heat sink to ambient thermal resistance Rhs-amb (°C/W)		Heat sink to ambient temperature rise Ths-amb (°C)	
	SimpoleD-11750		SimpoleD-11780	
15	20.5		15.2	
30	35.5		26.4	
45	44		38.3	
60	55		49.2	
75			56.3	
90			61.2	



\* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

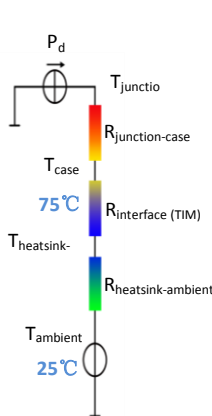
\*To calculate the dissipated power please use the following formula:  $P_d = P_e \times (1 - \eta_L)$ .

Pd - Dissipated power ; Pe - Electrical power ;  $\eta_L$  = Light efficiency of the LED module;

\*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



\*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula:  $\theta = (T_{hs} - T_a) / P_d$

$\theta$  - Thermal Resistance [°C/W] ;  $T_{hs}$  - Heatsink temperature ;  $T_a$  - Ambient temperature ;

\*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is  $R_{\text{junction-case}}$ , the thermal resistance of the TIM outside the package is  $R_{\text{interface (TIM)}}$  [°C/W], the thermal resistance with the

heat sink is  $R_{\text{heatsink-ambient}}$  [°C/W], and the ambient temperature is  $T_{\text{ambient}}$  [°C].

\*Thermal resistances outside the package  $R_{\text{interface (TIM)}}$  and  $R_{\text{heatsink-ambient}}$  can be integrated into the thermal resistance  $R_{\text{case-ambient}}$  at this point. Thus, the following formula is also used:

$$T_{\text{junction}} = (R_{\text{junction-case}} + R_{\text{case-ambient}}) \cdot P_d + T_{\text{ambient}}$$